GDS Import Wizard V5.6 Manual

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2022-06-24



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About GDS Import Wizard

A smart tool to translate GDSII to 3DLayout EDB quickly:

- Extract nets from GDS and import to EDB
- Extract accurate material property from IRCX
- Extract accurate layer thickness and stackup from IRCX
- Automatic generate control xml for AEDT GDSII Importing
- Automatic create Via Group and SnapViaGroups
- Automatic generate components on top and bottom layer for easier port setup
- Automatic generate TSV Insulation coating
- Synchronous import to AEDT when EDB prepared
- Automatic detect and fix of small gaps between layers to avoid mesh Issue (New in V4.0)
- Support sheet layers to simplify thinner metal layer mesh e.g. 0.001um (New in V4.0)
- support to generate temperature dependent material (New in V5.0)
- Add CSV input template to provide more flexible input for other Technology File (New in V5.0)
- Support New TSV Layer feature in 3D Layout 2022R1 (New in V5.0)
- Support ConvertPolygonToCircle Feature to reduce mesh(New in V5.0)
- More flexible setting options and enhanced command line(No-GUI) support(windows and Linux)



ANSYS workflow for 2.5D/3D SI Interpower Simulation

Integrated with ANSYS AEDT

Option1:

- ✓ TSMC IRCX
- ✓ GDS File

Option2:

- ✓ Customized Tech file (CSV)
- ✓ GDS File

GDSImportWizard

- ✓ Net name extract
- ✓ Stackup
- ✓ Layer thickness
- ✓ Material properties
- ✓ Via Groups
- ✓ Snap Primitives
- ✓ More...



HFSS 3D Layout

- ✓ S-parameter Extraction
- ✓ Crosstalk
- ✓ SSN
- ✓ Eye opening
- ✓ PDN
- ✓ Thermal-EM Co-simulation

Step 1

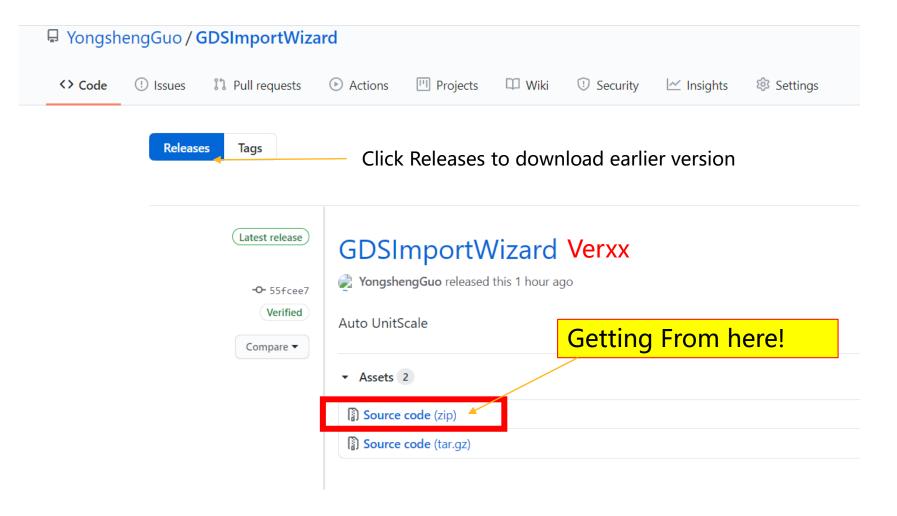
Step 2

Step 3

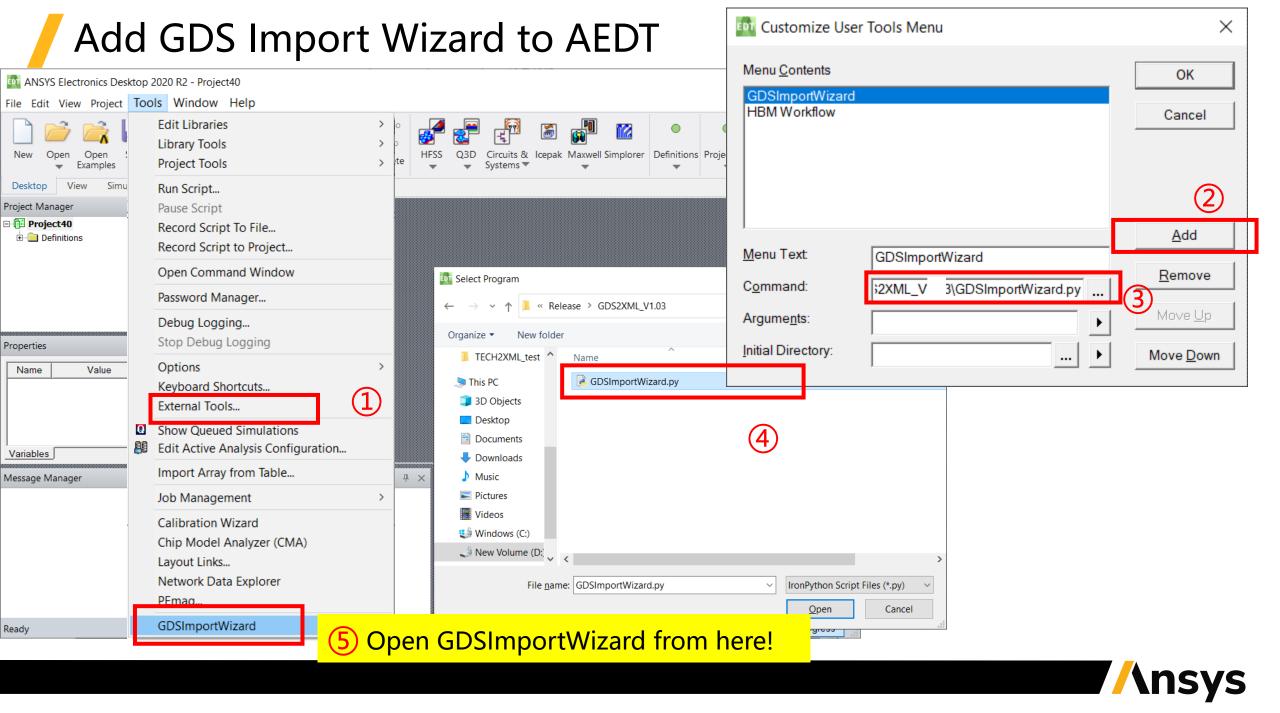


Get the latest GDSImportWizard Tool

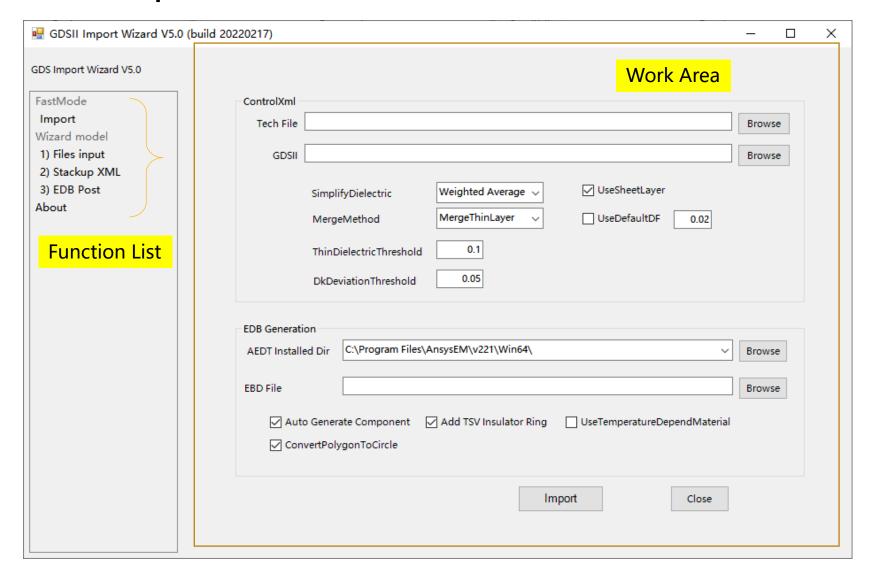
https://github.com/YongshengGuo/GDSImportWizard/releases/latest







GDS Import Wizard V5.0

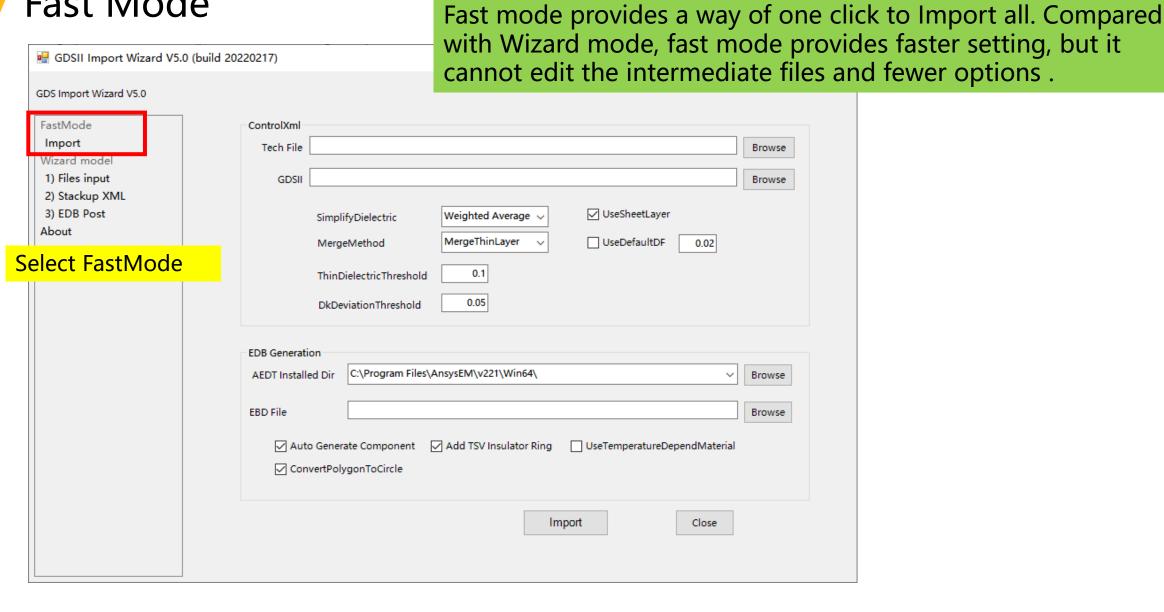




Running in Fast Mode

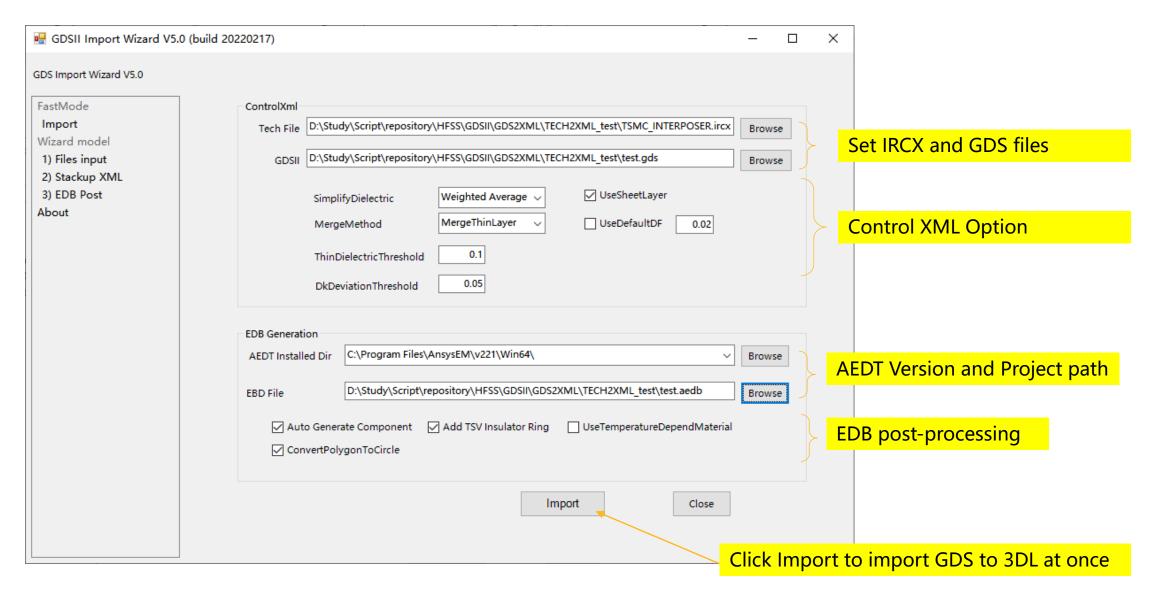


Fast Mode





Fast Mode

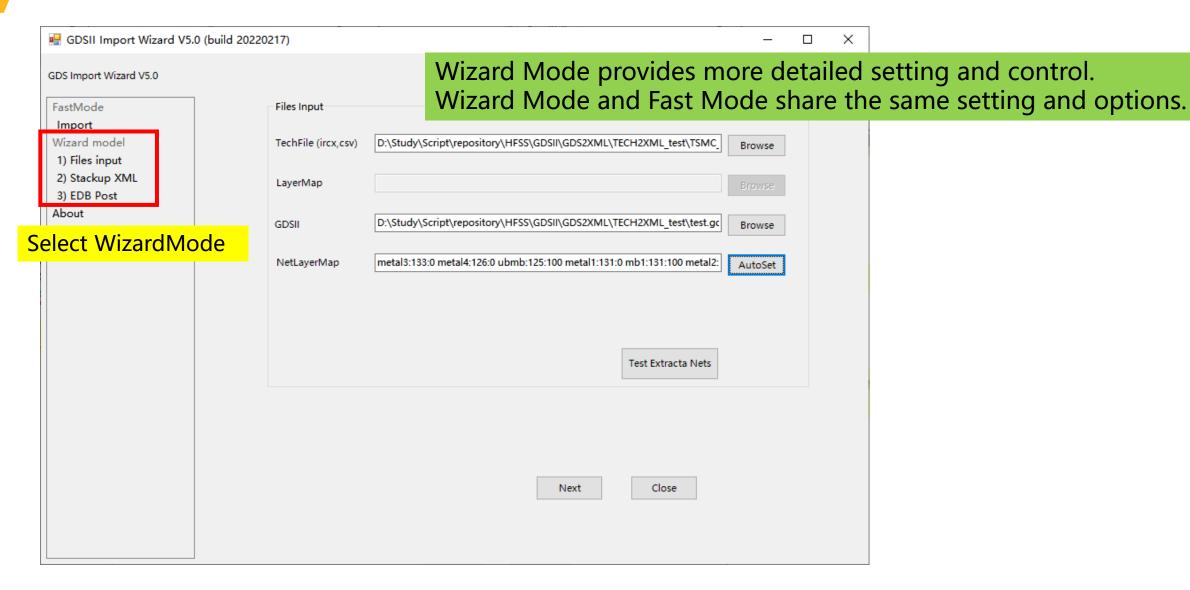




Running in Wizard Mode

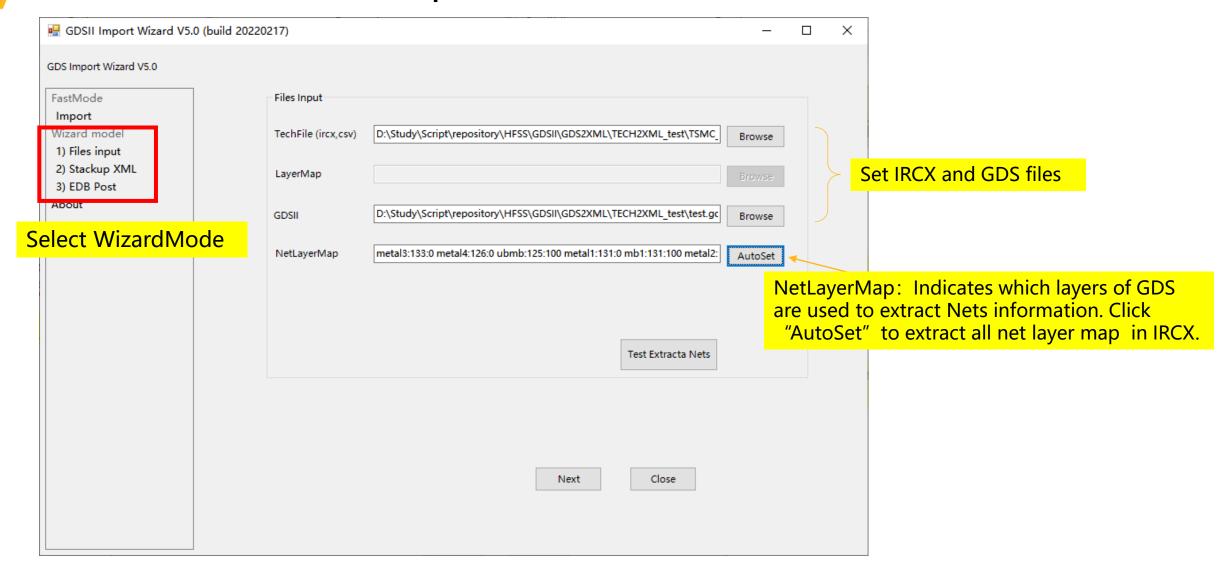


Fast Mode



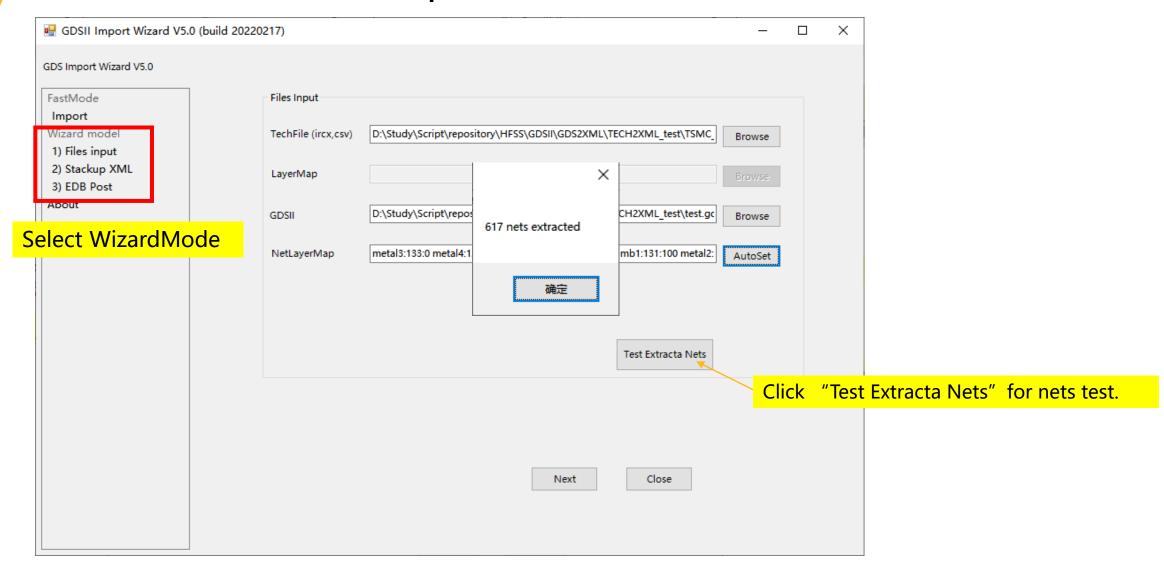


Fast Mode – 1) Files input



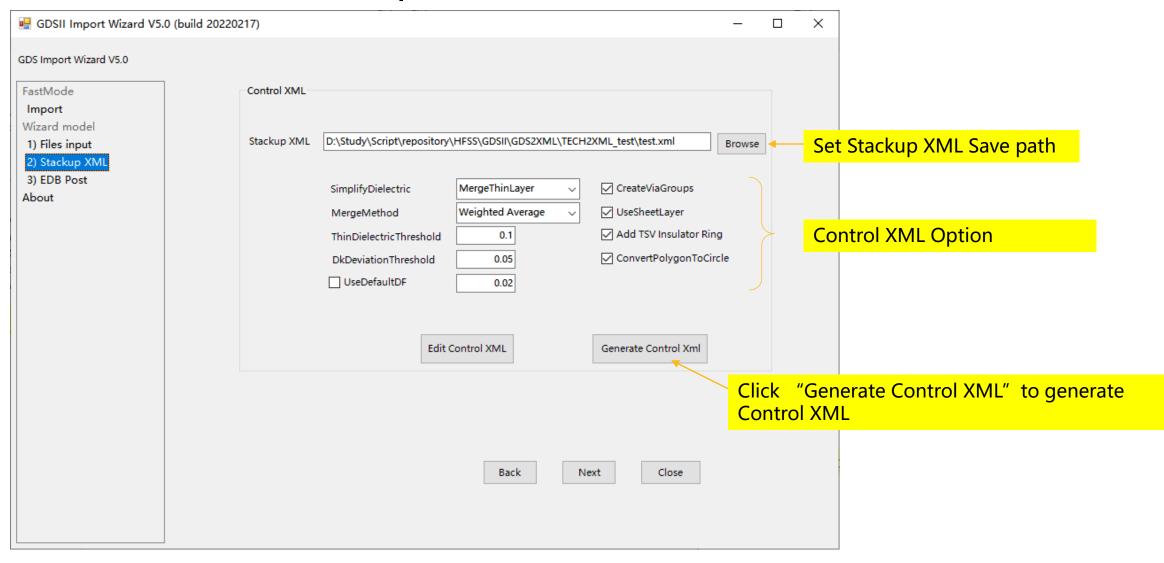


Fast Mode – 1) Files input



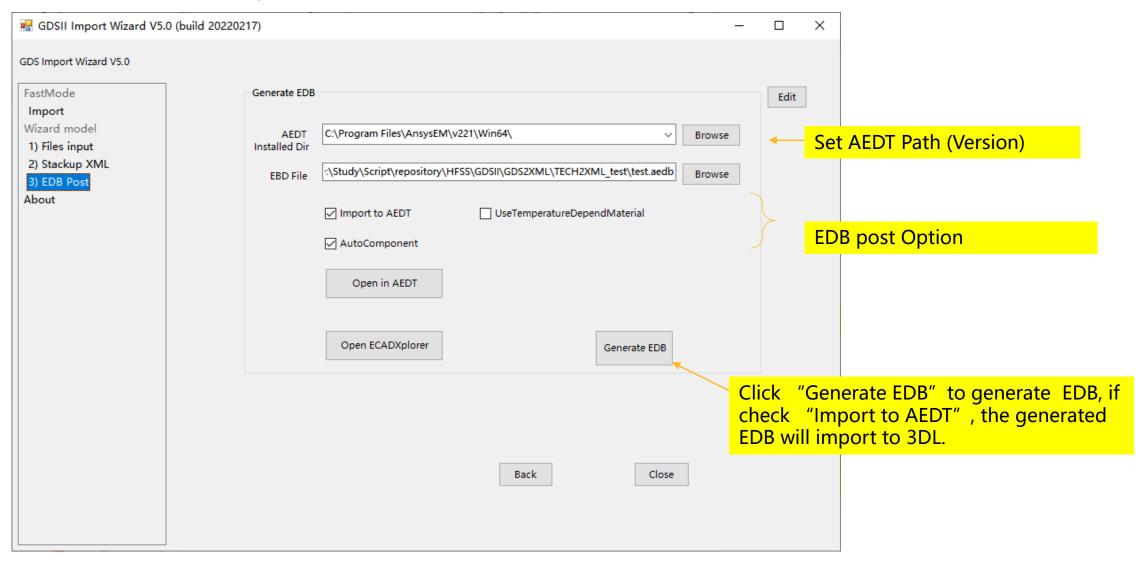


Fast Mode – 2) Stackup XML





Fast Mode – 3) EDB Post





Running in windows command line



Running in batch mode - Windows

Eg1. Configure from system environment:

- set AedtInstallDir=C:\Program Files\AnsysEM\AnsysEM21.1\Win64
- set GdsFile=D:\HFSS\GDSII\GDS2XML\TECH2XML_test\test.gds
- set TechFile=D:\HFSS\GDSII\GDS2XML\TECH2XML test\TSMC INTERPOSER.ircx
- set path=% AedtInstallDir %\common\IronPython;%path%
- ipy64 GDSImportWizard.py -batch

Eg2. Configure from command arguments:

- set AedtInstallDir=C:\Program Files\AnsysEM\AnsysEM21.1\Win64
- set path=% AedtInstallDir %\common\IronPython;%path%
- ipy64 GDSImportWizard.py –GdsFile "D:\HFSS\GDSII\GDS2XML\TECH2XML_test\test.gds" TechFile
 "D:\HFSS\GDSII\GDS2XML\TECH2XML test\TSMC INTERPOSER.ircx"

Note: system environment and command arguments could be mixed.



Running in batch mode - Windows

- A short command is supported:
 - ipy64 GDSImportWizard.py gdspath
 - ipy64 GDSImportWizard.py gdspath edbpath
- Eg3. short command
 - ipy64 GDSImportWizard.py "D:\HFSS\GDSII\GDS2XML\TECH2XML_test\test.gds" —TechFile
 "D:\HFSS\GDSII\GDS2XML\TECH2XML test\TSMC INTERPOSER.ircx"



Running in Linux terminal command



Running in batch mode - Linux

Eg1. Configure from system environment:

- export AedtInstallDir='/home/ansys/app/AnsysEM20.1/Linux64'
- export GdsFile=/home/ansys/yguo/test/test.gds
- export TechFile=/home/ansys/yguo/test/TSMC_INTERPOSER.ircx
- export ipy64="\$AedtInstallDir /common/mono/Linux64/bin/mono \$AedtInstallDir /common/IronPython/ipy64.exe"
- \$ipy64 GDSImportWizard.py

Eg2. Configure from command arguments:

- export AedtInstallDir='/home/ansys/app/AnsysEM20.1/Linux64'
- export ipy64="\$AedtInstallDir /common/mono/Linux64/bin/mono \$AedtInstallDir /common/IronPython/ipy64.exe"
- \$ipy64 GDSImportWizard.py –GdsFile "D:\HFSS\GDSII\GDS2XML\TECH2XML_test\test.gds" TechFile "D:\HFSS\GDSII\GDS2XML\TECH2XML_test\TSMC_INTERPOSER.ircx"

Note: system environment and command arguments could be mixed.



Running in batch mode - Linux

- A short command is supported:
 - ipy64 GDSImportWizard.py gdspath
 - ipy64 GDSImportWizard.py gdspath edbpath
- Eg3. short command
 - export AedtInstallDir='/home/ansys/app/AnsysEM20.1/Linux64'
 - export ipy64="\$aedtInstallPath/common/mono/Linux64/bin/mono \$aedtInstallPath/common/IronPython/ipy64.exe"
 - \$ipy64 GDSImportWizard.py "D:\HFSS\GDSII\GDS2XML\TECH2XML_test\test\gds" TechFile "D:\HFSS\GDSII\GDS2XML\TECH2XML_test\TSMC_INTERPOSER.ircx"



Options Setting



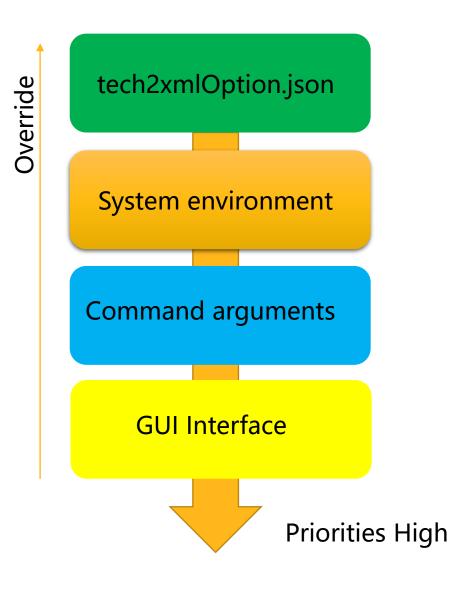
Options Parameters in GDS Import Wizard

- There are Four ways to set the options for GDS Import Wizard
 - 1) By configure file: tech2xmlOption.json (in same directory with toolkit)
 - 2) By system environment variables
 - 3) Set the parameters in command arguments.
 - 4) Set in GUI.

These three methods will achieve the same effect, but with different priorities.



Options Priorities



If the same parameter given in multiple places, the higher priority parameter will take precedence.

As one example, if one parameter is given in System environment and tech2xmlOption.json at the same time, System environment value will have high priorities and take precedence.

GUI Interface have the highest priority, Command arguments System environment and tech2xmlOption.json setting will be used as initial values of GUI input elements.



Options

Options	Defalut Value	Description							
		Stackup XML Parameters							
InputType	0	0: Ircx, others: not define							
UseShortMergeLayerName	True	changing is not recommended							
		0: NoSimplify, No Merge on Dielectric, exact layers in IRCX							
SimplifyDieletricMethod	1,	1 : MergeThinLayer, Merge layer thinner than a specific value							
		2:BlockMerge, use average DK on all layers except substrate							
MergeDielectricMethod	0	0: Weighted Average , 1: Weighted Average , 2: Kraszewski equation, 3: Landau equation, 4: Lichtenecker							
	ŭ	equation							
ThinDielectricThreshold	0.1	0.1: Merge layer when layer thickness<0.1um, default unit um							
DkDeviationThreshold	0.05 or 5%	0.05: Merge layers when dk difference less then 10%							
FixedSmallLayerGap	0.005	0.005: Fix small air gap between layers less then 0.005um, default unit um							
UseDefaultDF	True	True: If not hav df value in technology, a default df value will be used							
	True	false: If not hav df value in technology, will set df =0							
DefaultDF	0.02	set for default df value							
NotUseDfonSubstrate	True	True: default df value will never used on Substrate layer(Silicon material), it is recommended to set as True.							
UseSheetLayer	True	True: set the layers as 0um when it small then "SheetLayerThreshold", which will avoid to generatelarge number							
·		of tiny meshes							
SheetLayerThreshold	0.0015	0.0015: if "UseSheetLayer" is True, layers which < 0.0015um will set to zero thickness(treat as 2D sheet object)							
CreatViaGroups	True	True: ViaGroups will be implemented on via layers							
CreatViaGroupsOption	Default	Default: "Method:proximity,Tolerance:5um,CheckContainment:true",							
Creativiadioupsoption	Delauit	Option: "Method:range,Persistent:false,Tolerance:1um"							
NotUseViaGroupsOnLayers	".*tsv.*,pmb"	Regular expressions are used, don't create ViaGruops if layer name match anyone of list.							
Ignorol avorsPog	"air,ctm.*,cbm.*"dtce.*"	layers will not import into 3D Layout. Regular expressions are used, and ignoreLayerNames are seprate with							
IgnoreLayersReg	air,ctin. ,cbin. atce.	comma or space							
Toytlaverman	None	Text layers indicate for net extraction, None will use all text layer in technology files. User could set it accrond the							
TextLayermap	NOTIC	rule: "ubmb:125:100, "ubump:125:0"							
ConvertPolygonToCircle	True	True: will convert all polygons on a layer to circles, only support from AEDT 2022R1							
ConvertPolygonToCircleRatio	0.9	polygons with Circle Ratio 0.9 will convert to circles, valid when ConvertPolygonToCircle as True							



Options

Path Parameters								
TechFile	None	input: techFile path (Absolute), must set						
LayerMapFile	None	input: layerMapFile path (Absolute), not used						
GdsFile	None	input: gdsFile path (Absolute), must set						
AedtInstallDir	None	input: AEDT installtion path (Absolute), must set to do edb post						
ControlXmlPath	None	output: controlXmlPath (Absolute), optional						
edbPath	None	output: edbPath (Absolute), optional						
		Gds post Parameters						
OpenInAedt	True	true: will open EDB when the conversion is completed						
AutoComps	True	true: will automatic generation device, easy port creation						
CompLayerList	1,-1	index for which layers will generate components, 1 indicate top layer, -1 indicate bottom layer, and so on.						
ComponentPinsTolerance	10	Pins spacing less than 10 times pad diameter with each other will be considered as a component						
AutoTSVCoat	True	true: will automatic generation tsv insulator						
DissolveViaGroup	False	true: dussikve all groups or component before doing edb post processing						
UseTemperatureDependMaterial True		true: will generate temperature dependance material if TC1/TC2 given in material defintion						



Customized Technology File-CSVTech_overlapping_template



CSV Tech overlapping template

- The CSV format template provide an easy way to define Customized Technology File.
- You could find a demo file in the folder of the toolkit as CSVTech overlapping template.csv
- overlapping template is suited for any stackup, the dielectrics and metals are defined separately.
- The follow pages will give the details the overlapping template.



CSVTech_overlapping_template.csv

NO	LayerName	Туре	LayerMap	TextLayerMap	Thickness	Height	LowerLayer	UpperLayer	DK	DF	Cond	TC1	TC2	Tref	
-	LUF1	D			35	107.64			3.7						
19	IMD1a	D			0.05	100.75			8.1						
20	ILD	D			0.75	100			4						<u> </u>
21	Lsubstrate	D			100	0			11.9		10				<u> </u>
22	PASSB1	D			0.8	-0.8			6.7						1
23	PASSB2b	D			2	-2.8			6.7						1
24	PASSB2a	D			0.4	-3.2			6.7						<u> </u>
25	underFill_C	D			0.001	-3.201			6.7						1
26	ubump	С	170;0 74;0	125;0	0.001	142.639					5.80E+07	0.00E+00	0.00E+00	25.00	1
27	metal4	С	74;0		1.45	105.19					5.80E+07	3.89E-03	-1.50E-07	25.00	1
28	metal3	С	33;40		0.85	103.565					5.80E+07	3.63E-03	-1.39E-06	25.00	<u> </u>
29	metal2	С	32;40		0.85	102.12					5.80E+07	3.63E-03	-1.39E-06	25.00	1
30	Octm	С			0.08	101.793					5.80E+07	0.00E+00	0.00E+00	25.00	1
31	Lcbm	С			0.2	101.575					5.80E+07	0.00E+00	0.00E+00	25.00	1
32	2 metal1	С	31;40		0.85	100.675					5.80E+07	3.63E-03	-1.39E-06	25.00	1
33	mb1	С	31;100		0.001	-0.801					5.80E+07	0.00E+00	0.00E+00	25.00	1
34	1 ubmb	С	170;100	125;100	0.001	-3.201					5.80E+07	0.00E+00	0.00E+00	25.00	1
36	via4	V	86;0				metal4	ubump			5.80E+07				1
37	7 via3	V	85;0				metal3	metal4			5.80E+07				1
38	3 via 2	V	52;40				metal2	metal3			5.80E+07	3.63E-03	-1.39E-06		<u> </u>
39	ctm_via	V					ctm	metal2			5.80E+07	0.00E+00	0.00E+00		<u> </u>
40	cbm_via	V					cbm	metal2			5.80E+07	0.00E+00	0.00E+00		<u> </u>
42	l via1	V	51;40				metal1	metal2			5.80E+07				<u> </u>
42	2 tsv	V	251;0 86;0				mb1	metal1			5.80E+07				<u> </u>
43	3 pmb	V	5;100				ubmb	mb1			5.80E+07				<u> </u>
44	1tsv	I			0.15				4						1

CSVTech_overlapping_template.csv is in the folder of the toolkit.



Column Definition - CSV Tech overlapping template

- 1. LayerName is the names will be uesd in 3D Layout stackup, should be present.
- 2. Type, C: Conductor/Metal layer, V: Via layer, D: Dielectric layer, I: Insulating layer
 - Via Group and SnapViaGroups will be implemented on all Via layers.
 - Insulating layer is designed to define TSV insulation thickness, it must have a LayerName that have defined in Via Layers, or will be ignore
- 3. LayerMap indicates the layer mapping in GDS file.
 - Conductor/Metal and Via layer must have LayerMap value or will be ignore.
 - Multiple layermap Mapping could set to one layer separated with space, e.g. 86;0 85;0
- 4. TextLayerMap indicates which layer used to extract net list in GDS,
 - the layermap in GDS should have net information.
- 5. Thickness is set for Dielectrics/ Metals/Vias layer thickness, the default unit is um.
- 6. Height indicates position of the layer in stackup
 - All Height define in the lower of the layer, dielectrics Layers or Metal/Vias layers will be reordered by Height value, respectively.
 - If dielectrics Height not give, the height will be obtained by accumulating the thickness of dielectrics layer (invert order)
 - If Metal and Vias Height not give, the height will be obtained by accumulating the thickness of Metal and Vias layer (invert order)
 - The last dielectric layer is the origin, all height (D/C/V) value refer to this value, negative value is accepted.

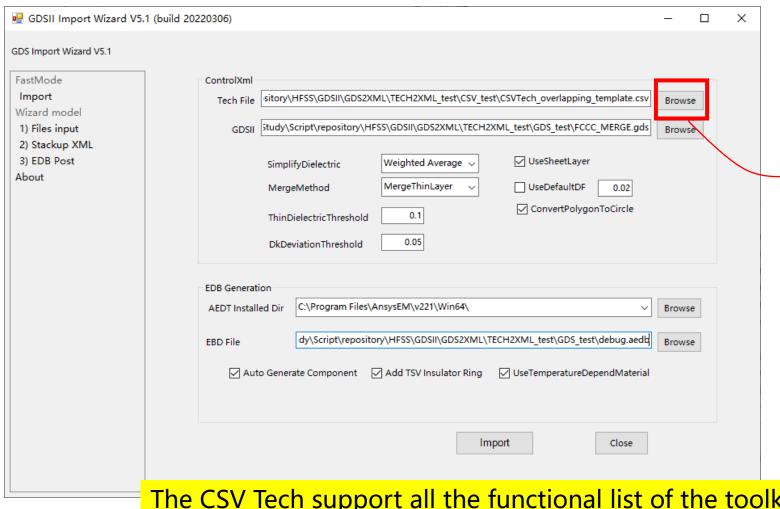


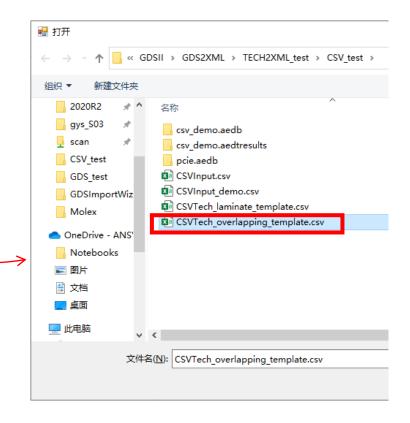
Column Definition - CSV Tech overlapping template

- 7. LowerLayer, UpperLayer defined the start and end layer of via layer
 - If LowerLayer, UpperLayer not give, the adjacent layers will set to LowerLayer, UpperLayer
 - LowerLayer, UpperLayer determines the thickness of the via layer, which have higher priority the via Thickness property
- 8. DK, DF, Cond is used to set Material properties of the layers
- 9. TC1, TC2, Tref is the temperature coefficient of conductivity, use for corner analysis
 - temperature-dependent material (conductivity) will be used if check UseTemperatureDependMaterial option in GUI
 - The formular is Cond/(1+(TC1*(\$Temp-Tref))+(TC2*(\$Temp-Tref)**2))
 - Tref is the base temperature, which defines the current conductivity



Use CSV Tech as input





The CSV Tech support all the functional list of the toolkit.



Customized Technology File-CSVTech_laminate_template



CSV Tech laminate template

- The CSV format template provide an easy way to define Customized Technology File.
- You could find a demo file in the folder of the toolkit as CSVTech_laminate_template.csv
- Laminate template provides a simplified then input the overlapping template, the dielectrics and metals are defined in laminate mode, more like PCB/Package application.
- Laminated CSV assume all the dielectrics is filled in Metal/Via layers and align with these layers.
- The follow pages will give the details the overlapping template.



CSVTech_ laminate_template.csv

NO	LayerName	Туре	LayerMap	TextLayerMap	Thickness	Height	DK	DF	Cond	TC1	TC2	Tref	
1	TOP_UBM	С	214;0	214;0	44.5		4	0.02	5.80E+07				
2	PI1	V	11;0		3		4	0.02	5.80E+07				
3	RDL1	С	1;0		4		4	0.02	5.80E+07				
	PI2	V	12;0		3		4	0.02	5.80E+07				
	RDL2	С	2;0		4		4	0.02	5.80E+07				
(PI3	V	13;0		3		4	0.02	5.80E+07				
7	RDL3	С	3;0		4		4	0.02	5.80E+07				
	tsv	V	14;0		3		4	0.02	5.80E+07				
9	RDL4	С	4;0		4		4	0.02	5.80E+07				
10	PI5	V	15;0		3		4	0.02	5.80E+07				
11	BOT_UBM	С	215;0		58		4	0.02	5.80E+07				
12	tsv	I			0.15		4						
										_			

Laminated CSV assume all the dielectrics is filled in Metal/Via layers and align with these layers. CSVTech_ laminate_template.csv is in the folder of the toolkit.



Column Definition - CSV Tech laminate template

- 1. LayerName is the names will be uesd in 3D Layout stackup, should be present.
- 2. Type, C: Conductor/Metal layer, V: Via layer, D: Dielectric layer, I: Insulating layer
 - Dielectric layer (type D) should be never present in this laminate template.
 - The start and end layer is considered as the adjacent layers
 - Via Group and SnapViaGroups will be implemented on all Via layers.
 - Insulating layer is designed to define TSV insulation thickness, it must have a LayerName that have defined in Via Layers, or will be ignore
- 3. LayerMap indicates the layer mapping in GDS file.
 - Conductor/Metal and Via layer must have LayerMap value or will be ignore.
 - Multiple layermap Mapping could set to one layer separated with space, e.g. 86;0 85;0
- 4. TextLayerMap indicates which layer used to extract net list in GDS,
 - the layermap in GDS should have net information.
- 5. Thickness must set for Metals/Vias layer thickness, the default unit is um.
- **6. Height** indicates position of the layer in stackup
 - All the height will be obtained by accumulating the thickness of Metal and Vias layer (invert order)
 - Manually set the height value is not suggested.

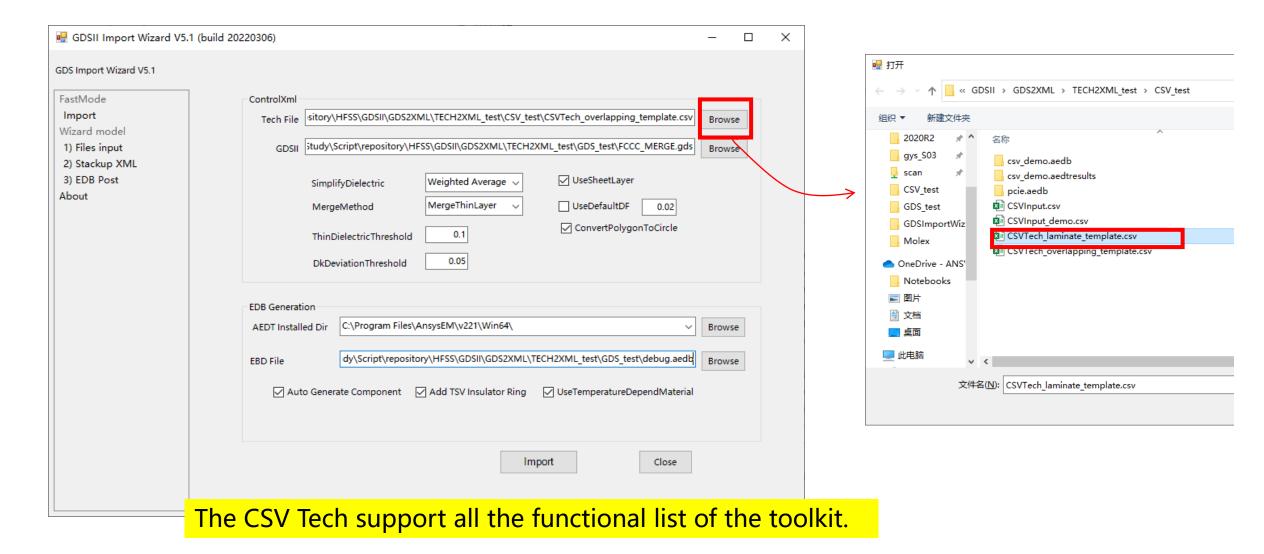


Column Definition - CSV Tech laminate template

- 7. DK, DF, Cond is used to set Material properties of the layers
 - DK, DF is used for the filled material
 - Cond is used for the metal/via material
- **8. TC1, TC2, Tref** is the temperature coefficient of conductivity, use for corner analysis
 - temperature-dependent material (conductivity) will be used if check UseTemperatureDependMaterial option in GUI
 - The formular is Cond/(1+(TC1*(\$Temp-Tref))+(TC2*(\$Temp-Tref)**2))
 - Tref is the base temperature, which defines the current conductivity



Use CSV Tech as input





Additional remarks



Restore default settings

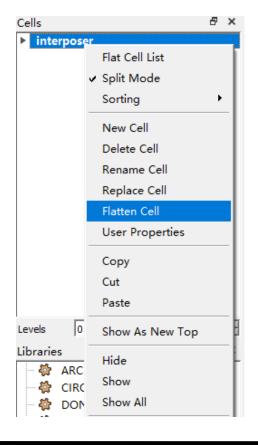
- If you have modified the configuration in tech2xmlOption.json and then want to restore to the default options. Just delete the file and run the toolkit again, tech2xmlOption.json will be made with default options.
- Don't forget that environment variables have higher priority. You need to check the settings in environment variables to make sure it is in purposeful.

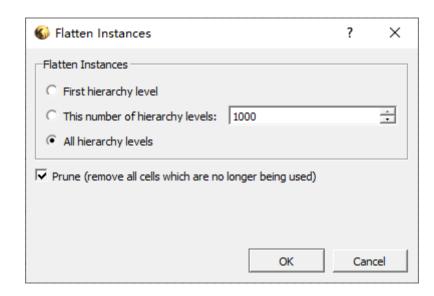
名称	修改日期	类型	大小
GDS Import Wizard V5.0 Manual-202	2/21/2022 12:19 PM	Foxit Reader PD	848 KB
🗦 GDSImportWizard.py	2/18/2022 9:14 AM	Python File	2 KB
gdslib.dll	3/6/2022 4:20 PM	应用程序扩展	1,334 KB
	3/6/2022 4:24 PM	JSON File	2 KB



About nets loss or error

- A known issue, hierarchy cells may bring wrong net coordinates and cause net lost or wrong (short or not right). Flatten Cells and then import will solve this issue.
- Below is a demo, how to use KLayout to flatten the cells.

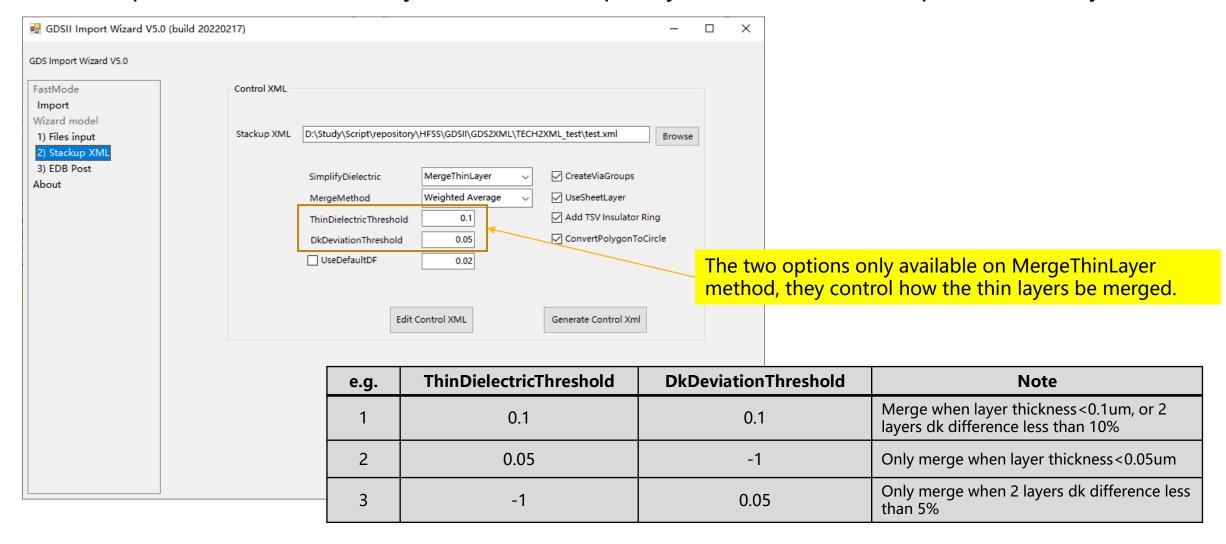






About Stackup simplification

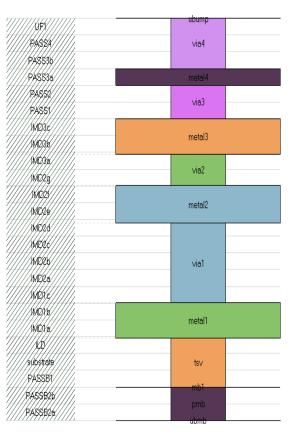
Stack simplification can effectively reduce the complexity of the model and improve efficiency

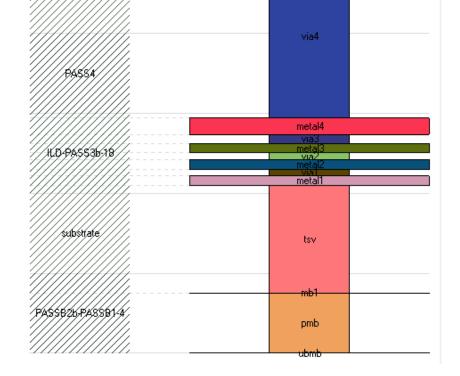


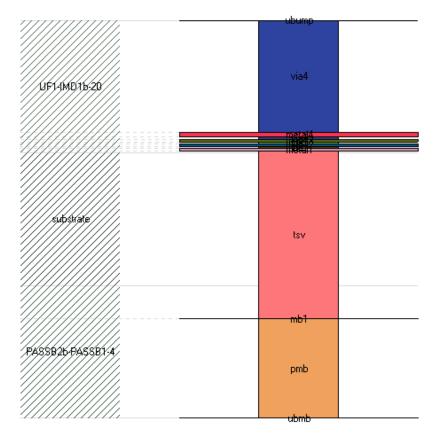


About Stack simplification

Merge Method Compare







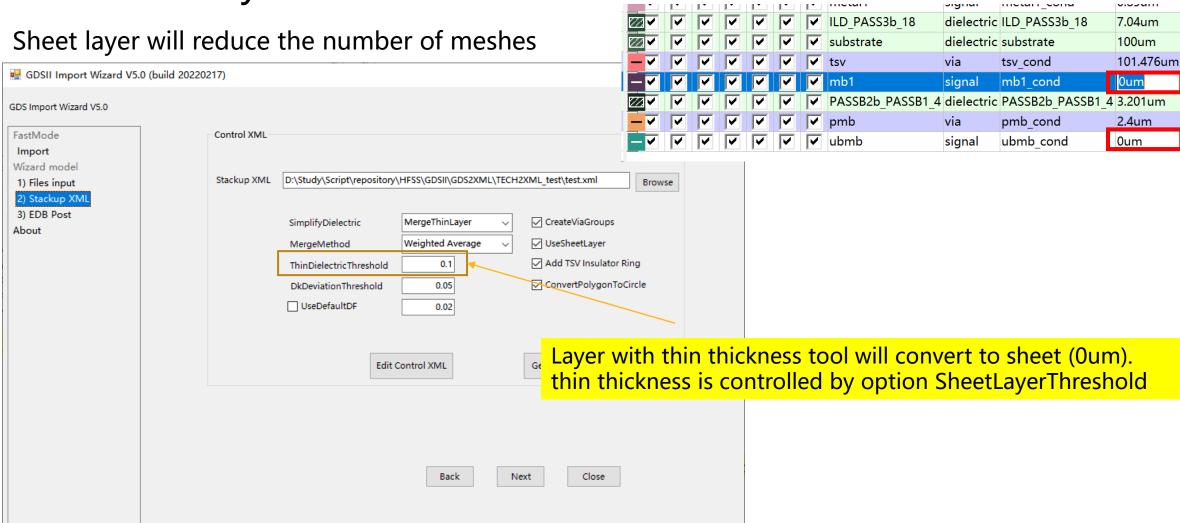
NoSimplify

MergeThinLayer

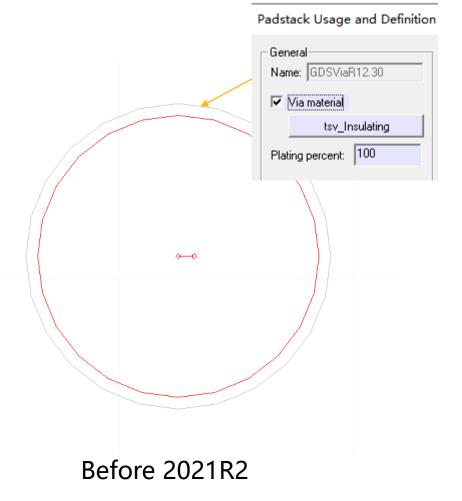
BlockMerge



Use Sheet Layer







AI RDL SiO₂ Metal 2 Metal 1 **▼** TSV Thickness Material TSV 0.15um tsv_Insulating New in 2022R1

TSV insulation is realized using 2 overlapping vias

TSV insulation is realized using layer TSV new property

GDS Import Wizard V5.0 will automatically choose the best way according to which AEDT version you run it.



ICap (integrated capacitors)

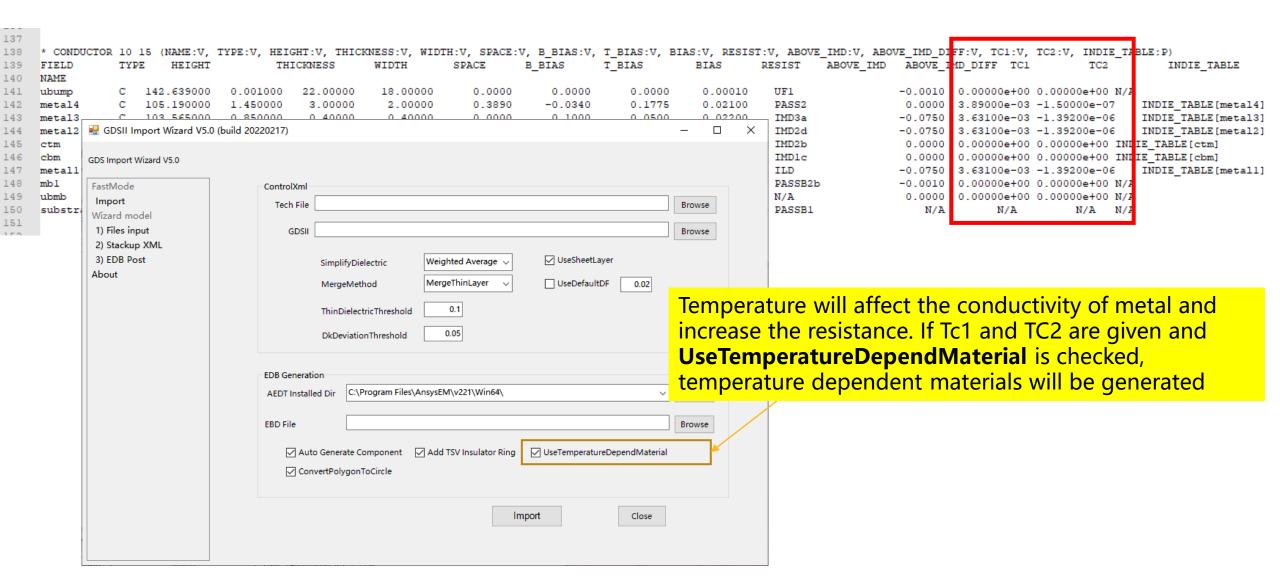


ICAP layers are ignored by default because it is thin and not have effect most of the time.

ICAP layers could be imported by setting IgnoreLayersReg to "air"

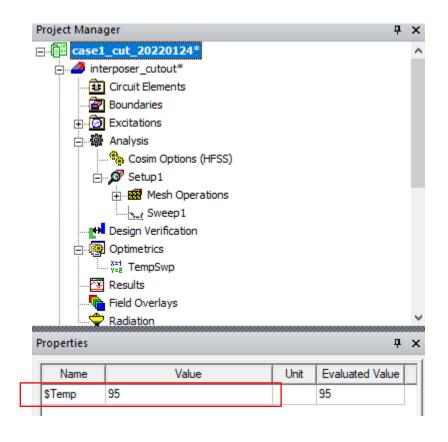


Temperature dependent material

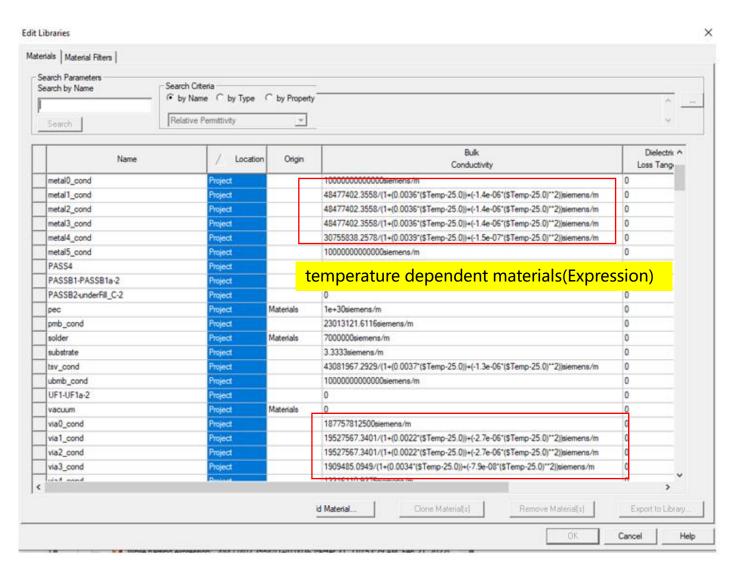




Temperature dependent material



Sweep the \$Temp variable will get the corner results at different temperatures





Multiple layermaps support in IRCX

TIIO									
1441	[LAYER N	MAPPING]							
1442	#substat	te is rev	verse	ed-to	ne NWEL	L			
1443	#via4 is	a4 is (ubump AND metal4)							
1444	#ubump t	ump_top_pin is ubump_pin mb_top_pin is ubmb_pin							
1445	#ubmb_to	omb_top_pin is ubmb_pin							
1446	#RC GDS LVS DFII								
1447	ubump	170	0 ;	ubur	qp	UBM;	drawing		
1448	metal4				metal4		AP; drawing		
1449	DUM4		74;1	L	DUM4		AP; dummy		
	metal3		33;4	10	metal3		M3;drawing		
	DUM3				DUM3		M3;dummy		
	metal2				2;41 🔻 m	etal2			
	DUM2				DUM2		M2;dummy		
	metall				metall		M1;drawing		
	DUM1				DUM1		M1; dummy		
		31;100							
	ubmb	170	:100	UBME	3	UBM;			
	via4	86;)	via4	1		drawing		
1459	via3	85;)				RV; drawing		
	via2				via2		VIA2; drawing		
1461	vial	251;0	51;4	10	vial		VIA1; drawing		
1462	tsv	251;0	tsv		TSV;dra	wing			
		251					dummyl		
		5;100							
1465	ubump_p	in	125;	0	ubm_top	_pin	UBM;pin		
		pin							
		pin							
							M2;pin		
							Ml;pin		
		n							
		77;0							
		88;0							
							VIA1; drawing		
	cbm_via	51;	40	cbm	via		VIA1; drawing		
1476									
	au .								
_									

Multiple layermaps are supported from V5.4, it only need add the new layermap to the corresponding metal layer and separated with ":".

Just append the dummy layermap to metal layer if you want consider the dummy metal.



Dummy Layer support in IRCX

```
"AedtInstallDir": null.
34
         "MergeDielectricMethod": 0,
35
         "SheetLayerThreshold": 0.0015,
36
         37
         "DefaultDF": 0.02,
38
                                                                                                      metal6
39
         "Precision": 6.
40
         "ControlXmlPath": null.
                                                                                   metal5
                                                                                                                      metal5_dummv_
         "Materials": [],
41
         "InputType": 0,
42
                                                                                   metal4
                                                                                                                      metal4 dummy
         "TextLayermap": {},
43
                                                                                                                      metal3_dummv
                                                                                   metal3
44
         "DummyLayerReg": [
             "metal\\d+"
45
                                                                                   metal2
                                                                                                                      metal2 dummy
46
                                                                                                       vial
                                                                                                                     metal1_dummy
                                                                                   metal1
          "Inimpledectricinreshold": 0.10000000000000001,
47
         "UnionPrimitivesOnLayer": [
48
49
             "ubmb",
50
             "ubump"
51
         "RemoveDuplicatePins": false,
52
         "UseTemperatureDependMaterial": false,
53
54
         "ImportDummyNet": true,
                                                                                                       tsv
55
         "OpenInAedt": true,
         "GdsFile": null.
56
         "InsulatorThickness": 1,
57
         "SimplifyDieletricMethod": 1,
58
         "IgnoreLayersReg": [
59
             "air",
60
61
             "ctm. *".
62
             "cbm. *".
             "dtce.*"
63
64
         "ImportDummyLayer": true
65
                                                                     Additional layers will be generated when
                                                                       "ImportDummyLayer" is set
```



CreatViaGroups Method

```
"ConvertPolygonToCircle": true,
"Default": nnll
"CreatViaGroupsOption": "Method:proximity, Tolerance: Sum, CheckContainment: true",
"NetWorking Composition": [
".*tsv.*",
"pmb"
],
```

"Method:proximity,Tolerance:5um,CheckContainment:true"

"Method:range, Persistent:false, Tolerance:1um"

```
<CreateViaGroups Method="proximity" Tolerance="5um" CheckContainment="true"</pre>
       <SnapViaGroups Method="areaFactor" Tolerance="3" RemoveUnconnected</p>
145
146
     🖯<Layer Name="51" Material="via1 cond" GDSDataType="40" TargetLayer="via1" StartLayer="meta:
       <CreateViaGroups Method="proximity" Tolerance="5um" CheckContainment="true" />
148
       <SnapViaGroups Method="areaFactor" Tolerance="3" RemoveUnconnected="true" />
149
150
     🗐 < Layer Name="251" Material="tsv cond" GDSDataType="0" TargetLayer="tsv" StartLayer="metal1
151
       <TSVProperties Thickness="0.15" Material="tsv Insulating" />
153
     🖆<Layer Name="5" Material="pmb cond" GDSDataType="100" TargetLayer="pmb" StartLayer="mb1" S
       </Laver>
      </Vias>
```

```
□<Layer Name="52" Material="via2 cond" GDSDataType="40" TargetLayer="via2" S
143
      <CreateViaGroups Method="range" Persistent="false" Tolerance="1um" />
      <SnapViaGroups Method="areaFactor" Tolerance="3" RemoveUnconnected="true" />
144
145
146
     ⊟<Laver Name="51" Material="via1 cond" GDSDataTvne="40" TarαetLaver="via1"
147
      <CreateViaGroups Method="range" Persistent="false" Tolerance="1um"</pre>
148
      <SnapViaGroups Method="areaFactor" Tolerance="3" RemoveUnconnected="true" />
149
      </Layer>
150
     <TSVProperties Thickness="0.15" Material="tsv Insulating" />
```

Note: Environment variables and command-line arguments could be set for this option.



Options in CSV Tech (from V5.6)

4	Α	В	С	D	Е	F	G	Н	1
1	NO	LayerName	Туре	LayerMap	TextLayerl	Thickness	Height	LowerLayer	UpperLayer
2	13	fill_in	D			0.001			
3	14	M4	С	31;0		0.001	0.002		
4	15	CTM2	С	67;3		0.0003	0.0006		
5	17	M3	С	28;0		0.0005	0		
6	21	via34	V	29;0				None	M4
7									
8		UseSheetLayer	О	FALSE					
9		FixedSmallLayerGap	О	0					
10		CreatViaGroups	О	FALSE					
11		AutoComps	0	FALSE					
12	#Note:								

Options in CSV Tech with Type as O or (Option).

Options in CSV Tech have highest priority then GUI and any other ways, it should be used with caution, which may cause mismatch between GUI and finally effective.



Ansys